

ABSTRACT

A semiconductor device includes a semiconductor substrate including an integrated circuit and an electrode. A resin layer is provided on a side of the semiconductor substrate where the electrode is formed and a wiring layer is formed on an area reaching from the electrode to a top of the resin layer. The electrode has a first rim part facing a periphery of the semiconductor substrate and a second rim part facing a center region of the semiconductor substrate. The resin layer is formed so as to overlap the second rim part, leaving out an area from the periphery of the semiconductor substrate to the first rim part of the electrode.